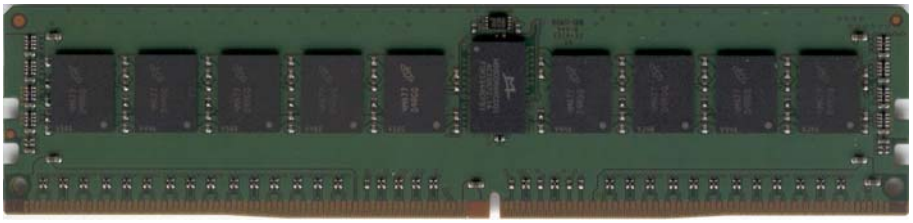
DTM68105A

8GB - 288-Pin 2Rx8 Registered ECC DDR4 DIMM



Features

- 288-pin JEDEC-compliant DIMM,133.35 mm wide by 31.25 mm high
- Operating Voltage: VDD/VDDQ = 1.2V (1.14V to 1.26V)
- VPP = 2.5V (2.375V to 2.75V)
- VDDSPD = 2.25V to 2.75V
- I/O Type: 1.2 V signaling
- On-board I^2C temperature sensor with integrated Serial Presence-Detect (SPD) EEPROM
- Data Transfer Rate: 17.0 Gigabytes/sec
- Data Bursts: 8 and burst chop 4 mode
- ZQ Calibration for Output Driver and On-Die Termination (ODT)
- Programmable ODT / Dynamic ODT during Writes
- Programmable CAS Latency: 9, 10, 11, 12, 13, 14, 15 and 16
- Bi-directional Differential Data Strobe signals
- Per DRAM Addressability is supported
- Write CRC is supported at all speed grades
- DBI (Data Bus Inversion) is supported(x8 only)
- CA parity (Command/Address Parity) mode is supported
- Supports ECC error correction and detection
- 16 internal banks
- SDRAM Addressing (Row/Col/BG/BA): 15/10/2/2
- Fully RoHS Compliant

Identification

DTM68105A 1Gx72
8GB 2Rx8 PC4-2133P-RE0-10

Performance range

Clock / Module Speed / CL-t_{RCD} -t_{RP}
1067 MHz / PC4-2133 / 16-16-16
1067MHz / PC4-2133 / 15-15-15
933 Hz / PC4-1866 / 14-14-14
933 Hz / PC4-1866 / 13-13-13
800 Hz / PC4-1600 / 12-12-12
800 Hz / PC4-1600 / 11-11-11
667 MHz / PC4-1600 / 10-10-10
667 MHz / PC4-1600 / 9-9-9

Description

DTM68105A is a registered 1Gx72 memory module, which conforms to JEDEC's DDR4-2133, PC4-2133 standard.

The assembly is Dual-Rank. Each rank is comprised of nine Micron 512Mx8 DDR4-2133 SDRAMs. One 4K-bit EEPROM is used for Serial Presence Detect and a combination register/PLL, with Address and Command Parity is also used.

Both output driver strength and input termination impedance are programmable to maintain signal integrity on the I/O signals in a Fly-by topology. A thermal sensor accurately monitors the DIMM module and can prevent exceeding the maximum operating temperature of 95C.

Speed Bin Table

Speed Bin				DDR4-2133P		DDR4-2133R		Unit	NOTE
CL-nRCD-nRP				15-15-15		16-16-16			
Parameter			Symbol	min	max	min	max		
Internal read command to first data			tAA	14.06[10] (13.50)[5,8]	18.00	15.00	18.00	ns	
Internal read command to first data with read DBI enabled			tAA_DBI	TBD	TBD	TBD	TBD	ns	
ACT to internal read or write delay time			tRCD	14.06 (13.50)[5,8]	-	15.00	-	ns	
PRE command period			tRP	14.06 (13.50)[5,8]	-	15.00	-	ns	
ACT to PRE command period			tRAS	33	9 x tREFI	33	9 x tREFI	ns	
ACT to ACT or REF command period			tRC	47.06 (46.50)[5,8]	-	48.00	-	ns	
	Normal	Read DBI							
CWL = 9	CL = 9	CL = 11 (Optional)[5]	$tCK_{(AVG)}$	1.5	1.6	Reserved		ns	1,2,3,4,7,10
			$tCK_{(AVG)}$	(Optional)[5,8]					
	CL = 10	CL = 12	$tCK_{(AVG)}$	Reserved		1.5	1.6	ns	1,2,3,7
CWL = 9,11	CL = 11	CL = 13	$tCK_{(AVG)}$	1.25	<1.5	Reserved		ns	1,2,3,4 ,6
			$tCK_{(AVG)}$	(Optional)[5,8]					
	CL = 12	CL = 14	$tCK_{(AVG)}$	1.25	<1.5	1.25	<1.5	ns	1,2,3,6
CWL = 10,12	CL = 13	CL = 15	$tCK_{(AVG)}$	1.071	<1.25	Reserved		ns	1,2,3,4 ,6
			$tCK_{(AVG)}$	(Optional)[5,8]					
	CL = 14	CL = 16	$tCK_{(AVG)}$	1.071	<1.25	1.071	<1.25	ns	1,2,3,6
CWL = 11,14	CL = 14	CL = TBD	$tCK_{(AVG)}$	Reserved		Reserved		ns	1,2,3,4
	CL = 15	CL = TBD	$tCK_{(AVG)}$	0.938	<1.071	Reserved		ns	1,2,3,4
	CL = 16	CL = TBD	$tCK_{(AVG)}$	0.938	<1.071	0.938	<1.071	ns	1,2,3
Supported CL Settings				(9),(11),12,(13),14,15 , 16		10,12,14,16		nCK	9,10
Supported CL Settings with read DBI				TBD		TBD		nCK	
Supported CWL Settings				9,10,11,12,14		9,10,11,12,14		nCK	

Speed Bin Table Notes:
Absolute Specification
- VDDQ = VDD = 1.20V +/- 0.06 V
- VPP = 2.5V +0.25/-0.125 V
- The values defined with above-mentioned table are DLL ON case.
- DDR4-1600, 1866, 2133 and 2400 Speed Bin Tables are valid only when Geardown Mode is disabled.

1. The CL setting and CWL setting result in tCK(avg).MIN and tCK(avg).MAX requirements. When making a selection of tCK(avg), both need to be fulfilled: Requirements from CL setting as well as requirements from CWL setting.

2. tCK(avg).MIN limits: Since CAS Latency is not purely analog - data and strobe output are synchronized by the DLL – all possible intermediate frequencies may not be guaranteed. An application should use the next smaller JEDEC standard tCK(avg) value (1.5, 1.25, 1.071, 0.938 or 0.833 ns) when calculating CL [nCK] = tAA [ns] / tCK(avg) [ns], rounding up to the next 'Supported CL', where tAA = 12.5ns and tCK(avg) = 1.3 ns should only be used for CL = 10 calculation.

3. tCK(avg).MAX limits: Calculate tCK(avg) = tAA.MAX / CL SELECTED and round the resulting tCK(avg) down to the next valid speed bin (i.e. 1.5ns or 1.25ns or 1.071 ns or 0.938 ns or 0.833 ns). This result is tCK(avg). MAX corresponding to CL SELECTED.

4. 'Reserved' settings are not allowed. User must program a different value.

5. 'Optional' settings allow certain devices in the industry to support this setting however it is not a mandatory feature. Refer to supplier's data sheet and/or the DIMM SPD information if and how this setting is supported.

6. Any DDR4-2133 speed bin also supports functional operation at lower frequencies as shown in the table which are not subject to Production Tests but verified by Design/Characterization.

7. DDR4-1600 AC timing apply if DRAM operates at lower than 1600 MT/s data rate.

8. For devices supporting optional down binning to CL=9, CL=11 and CL=13, tAA/tRCD/tRPmin must be 13.5ns or lower. SPD settings must be programmed to match. For example, DDR4-1600K devices supporting down binning to 1333MT/s should program 13.5ns in SPD bytes for tAAmin(Byte 24), tRCDmin (Byte 25), and tRPmin (Byte 26). DDR4-1866M devices supporting down binning to 1333MT/s or DDR4-1600K should program 13.5ns in SPD bytes for tAAmin (Byte 24), tRCDmin (Byte 25), and tRPmin (Byte 26).DDR4-2133P devices supporting down binning to 1333MT/s or DDR4-1600K or DDR4-1866M should program 13.5ns in SPD bytes for tAAmin (Byte 24), tRCDmin (Byte 25), and tRPmin (Byte 26).tRCmin (Byte 27, 29) also should be programmed accordingly. For example, 48.5ns (tRASmin + tRPmin = 35ns+ 13.5ns) is set to supporting optional down binning CL=9 and CL=11.

9. CL number in parentheses, it means that these numbers are optional.

10. DDR4 SDRAM supports CL=9 as long as a system meets tAA(min).

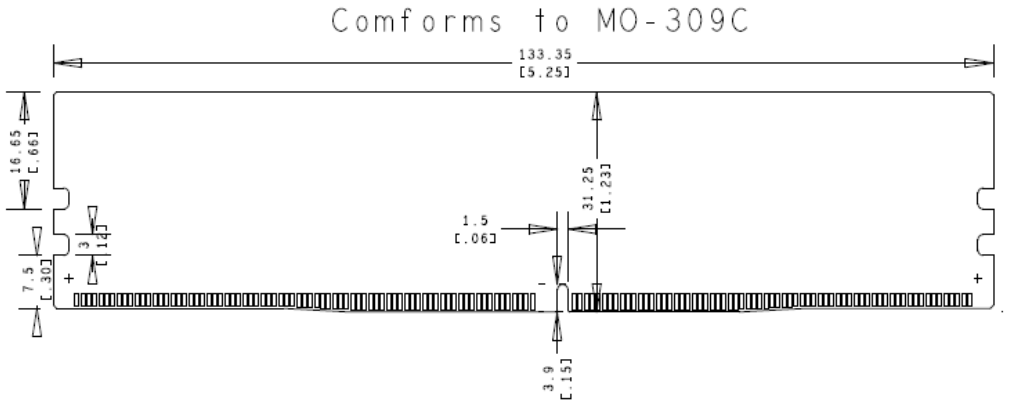
Pin Configuration

Front Side								Back Side							
1	12V,NC	37	V_{SS}	73	V_{DD}	109	V_{SS}	145	12V,NC	181	DQ29	217	V_{DD}	253	DQ41
2	V_{SS}	38	DQ24	74	CK0_t	110	DM5_n	146	V_{REFCA}	182	V_{SS}	218	CK1_t	254	V_{SS}
3	DQ4	39	V_{SS}	75	CK0_c	111	NC	147	V_{SS}	183	DQ25	219	CK1_c	255	DQS5_c
4	V_{SS}	40	DM3_n	76	V_{DD}	112	V_{SS}	148	DQ5	184	V_{SS}	220	V_{DD}	256	DQS5_t
5	DQ0	41	NC	77	V_{TT}	113	DQ46	149	V_{SS}	185	DQS3_c	221	V_{TT}	257	V_{SS}
6	V_{SS}	42	V_{SS}	78	EVENT_n	114	V_{SS}	150	DQ1	186	DQS3_t	222	PARITY	258	DQ47
7	DM0_n	43	DQ30	79	A0	115	DQ42	151	V_{SS}	187	V_{SS}	223	V_{DD}	259	V_{SS}
8	NC	44	V_{SS}	80	V_{DD}	116	V_{SS}	152	DQS0_t	188	DQ31	224	BA1	260	DQ43
9	V_{SS}	45	DQ26	81	BA0	117	DQ52	153	DQS0_c	189	V_{SS}	225	A10 / AP	261	V_{SS}
10	DQ6	46	V_{SS}	82	RAS_n / A16	118	V_{SS}	154	V_{SS}	190	DQ27	226	V_{DD}	262	DQ53
11	V_{SS}	47	CB4	83	V_{DD}	119	DQ48	155	DQ7	191	V_{SS}	227	RFU	263	V_{SS}
12	DQ2	48	V_{SS}	84	CS0_n	120	V_{SS}	156	V_{SS}	192	CB5	228	WE_n / A14	264	DQ49
13	V_{SS}	49	CB0	85	V_{DD}	121	DM6_n	157	DQ3	193	V_{SS}	229	V_{DD}	265	V_{SS}
14	DQ12	50	V_{SS}	86	CAS_n / A15	122	NC	158	V_{SS}	194	CB1	230	SAVE_n,NC	266	DQS6_c
15	V_{SS}	51	DM8_n	87	ODT0	123	V_{SS}	159	DQ13	195	V_{SS}	231	V_{DD}	267	DQS6_t
16	DQ8	52	NC	88	V_{DD}	124	DQ54	160	V_{SS}	196	DQS8_c	232	A13	268	V_{SS}
17	V_{SS}	53	V_{SS}	89	CS1_n	125	V_{SS}	161	DQ9	197	DQS8_t	233	V_{DD}	269	DQ55
18	DM1_n	54	CB6	90	V_{DD}	126	DQ50	162	V_{SS}	198	V_{SS}	234	A17, NC	270	V_{SS}
19	NC	55	V_{SS}	91	ODT1	127	V_{SS}	163	DQS1_c	199	CB7	235	C2,NC	271	DQ51
20	V_{SS}	56	CB2	92	V_{DD}	128	DQ60	164	DQS1_t	200	V_{SS}	236	V_{DD}	272	V_{SS}
21	DQ14	57	V_{SS}	93	CS2_n,C0,NC	129	V_{SS}	165	V_{SS}	201	CB3	237	CS3_n,C1,NC	273	DQ61
22	V_{SS}	58	RESET_n	94	V_{SS}	130	DQ56	166	DQ15	202	V_{SS}	238	SA2	274	V_{SS}
23	DQ10	59	V_{DD}	95	DQ36	131	V_{SS}	167	V_{SS}	203	CKE1	239	V_{SS}	275	DQ57
24	V_{SS}	60	CKE0	96	V_{SS}	132	DM7_n	168	DQ11	204	V_{DD}	240	DQ37	276	V_{SS}
25	DQ20	61	V_{DD}	97	DQ32	133	NC	169	V_{SS}	205	RFU	241	V_{SS}	277	DQS7_c
26	V_{SS}	62	ACT_n	98	V_{SS}	134	V_{SS}	170	DQ21	206	V_{DD}	242	DQ33	278	DQS7_t
27	DQ16	63	BG0	99	DM4_n	135	DQ62	171	V_{SS}	207	BG1	243	V_{SS}	279	V_{SS}
28	V_{SS}	64	V_{DD}	100	NC	136	V_{SS}	172	DQ17	208	ALERT_n	244	DQS4_c	280	DQ63
29	DM2_n	65	A12 / BC_n	101	V_{SS}	137	DQ58	173	V_{SS}	209	V_{DD}	245	DQS4_t	281	V_{SS}
30	NC	66	A9	102	DQ38	138	V_{SS}	174	DQS2_c	210	A11	246	V_{SS}	282	DQ59
31	V_{SS}	67	V_{DD}	103	V_{SS}	139	SA0	175	DQS2_t	211	A7	247	DQ39	283	V_{SS}
32	DQ22	68	A8	104	DQ34	140	SA1	176	V_{SS}	212	V_{DD}	248	V_{SS}	284	V_{DDSPD}
33	V_{SS}	69	A6	105	V_{SS}	141	SCL	177	DQ23	213	A5	249	DQ35	285	SDA
34	DQ18	70	V_{DD}	106	DQ44	142	V_{PP}	178	V_{SS}	214	A4	250	V_{SS}	286	V_{PP}
35	V_{SS}	71	A3	107	V_{SS}	143	V_{PP}	179	DQ19	215	V_{DD}	251	DQ45	287	V_{PP}
36	DQ28	72	A1	108	DQ40	144	RFU	180	V_{SS}	216	A2	252	V_{SS}	288	V_{PP}

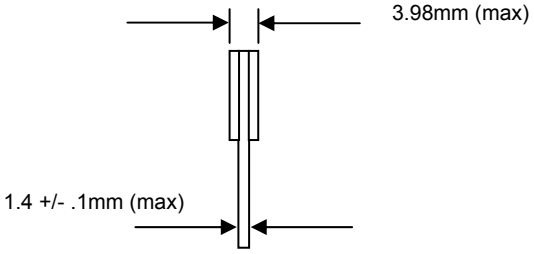
PIN DESCRIPTION

Name	Function
CB[7:0]	Data Check Bits
DQ[63:0]	Data Bits
DQS[8:0]_t, DQS[8:0]_c	Differential Data Strobes
DM[8:0]_n	Data Masks
CK_t[1:0], CK_c[1:0]	Differential Clock Inputs
CKE[1:0]	Clock Enables
CAS_n / A15	Multiplexed: Column Address Strobe or Address 15
RAS_n / A16	Multiplexed: Row Address Strobe or Address 16
CS[1:0]_n, CS[3:2]*	Chip Selects
ACT_n	Activate Command Input
WE_n / A14	Multiplexed: Write Enable or Address 14
C[2:0]	Chip ID Inputs
A[17:0]	Address Inputs
BA[1:0]	Bank Address select Inputs
BG[1:0]	Bank Group select Inputs
ODT[1:0]	On Die Termination Inputs
SA[2:0]	SPD Address
SCL	SPD Clock Input
SDA	SPD Data Input/Output
EVENT_n	Temperature Sensing
RESET_n	Reset for register and DRAMs
PARITY	Parity bit input for Addr/Ctrl
ALERT_n	CRC Error Flag or CMD/Addr Parity Flag Output
A12 / BC_n	Combination Input: Address12/Burst Chop
A10 / AP	Combination Input: Addr10/Auto-precharge
12V*	Optional Power Supply*
V_{PP}	Charge Pump Power
V_{SS}	Ground
V_{DD}	Power
V_{DDSPD}	SPD EEPROM Power
V_{REFCA}	Reference Voltage for CA
V_{TT}	Termination Voltage
NC	No Connection
RFU	Reserved for Future Use

* Not used



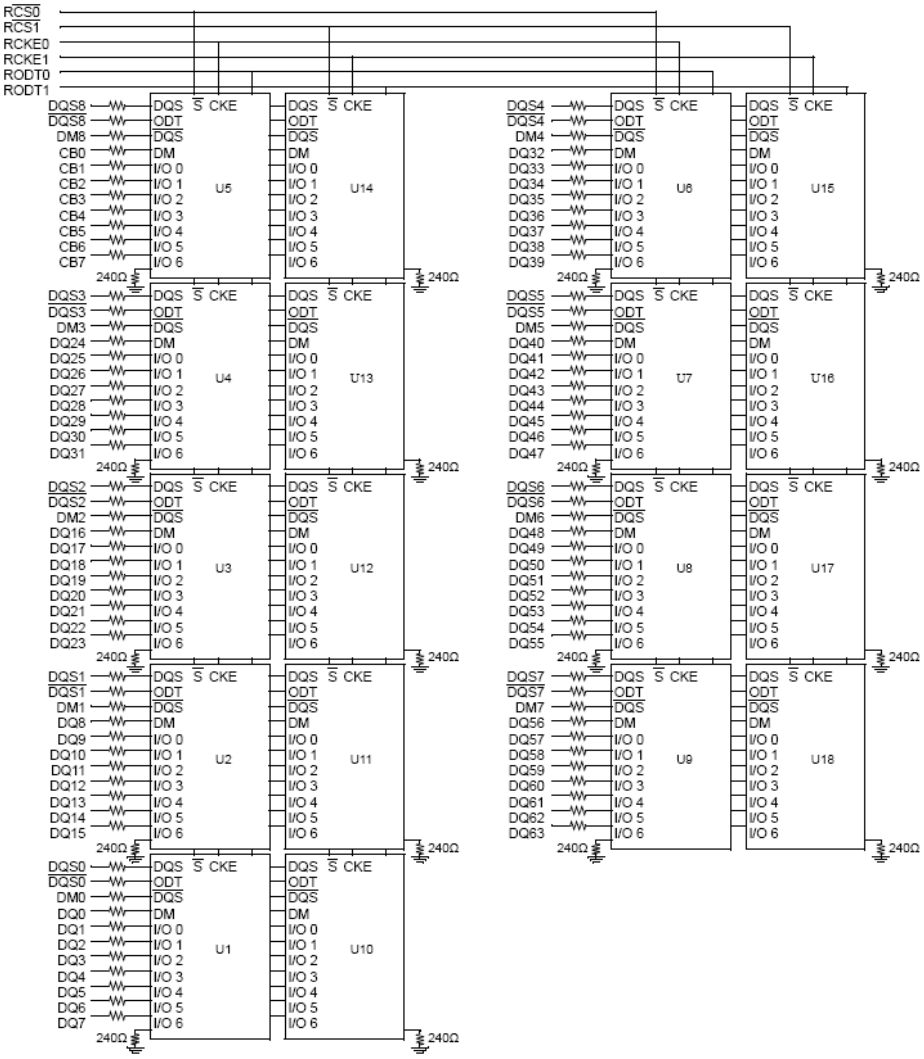
Side View

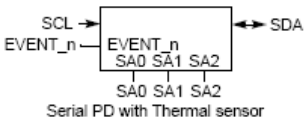


Notes:

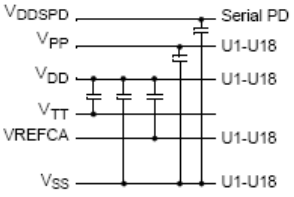
1. Tolerances on all dimensions except where otherwise indicated are ±.13. Reference JEDEC standard MO-309C.
2. All dimensions are expressed: millimeters [inches]

Functional Diagram



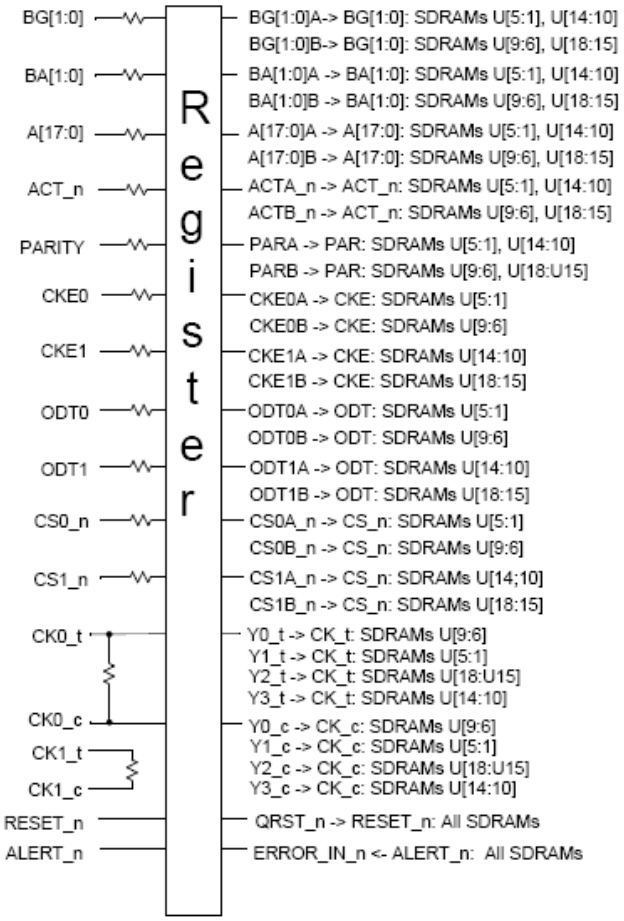


Serial PD with Thermal sensor



Notes:

1: Unless otherwise noted, resistor values are 15Ω ± 5%.
2: See the Net Structure diagrams for all resistors associated with the command, address and control bus.
3: ZQ resistors are 240Ω ±1%. For all other resistor values refer to the appropriate wiring diagram.



Notes:

1: CK0_t, CK0_c terminated with 120Ω ± 5% resistor.
2: CK1_t, CK1_c terminated with 120Ω ± 5% resistor but not used.
3: Unless otherwise noted resistors are 22Ω ± 5%.

DATARAM CORPORATION, USA Corporate Headquarters, P.O. Box 7528, Princeton, NJ 08543-7528;
Voice: 609-799-0071, Fax: 609-799-6734; www.dataram.com